

In the Claims:

Please cancel claims 1-11 and 13. Please amend claims 12 and 15-16. The claims are as follows.

1-11. (Canceled)

12. (Currently Amended) A method for forming an electronic structure, comprising:

providing a semiconductor device;

electrically coupling the semiconductor device to a substrate;

adhesively coupling a stiffener ring to the substrate, wherein the stiffener ring surrounds the semiconductor device, and

adhesively coupling a cover plate to a portion of a top surface of the semiconductor device with a first adhesive and to a portion of [[a]] the top surface of the stiffener ring with a second adhesive, wherein a modulus of the first adhesive is less than a modulus of a second adhesive, and wherein the first adhesive has an elastic modulus less than about 500 psi.

13. (Canceled)

14. (Original) The method of claim 12, further comprising a heat sink, wherein the heat sink is coupled by a third adhesive to a portion of a top surface of the cover plate.

15. (Currently Amended) The method of claim 14, wherein an elastic modulus of the third adhesive is less than the elastic modulus of the second adhesive, wherein the third adhesive has a

lower elastic modulus than a second adhesive.

16. (Currently Amended) The method of claim 14, wherein the elastic modulus of the third adhesive is about equal to the elastic modulus of the first adhesive.

17. (Original) The method of claim 12, wherein the substrate has a compliance range of 10^4 psi to 3×10^6 psi.

18. (Original) The method of claim 12, wherein the semiconductor device includes a semiconductor chip.

19. (Original) The method of claim 12, wherein the substrate is selected from a group consisting of a chip carrier and a printed circuit board.

20. (Original) The method of claim 12, wherein the substrate comprises an organic material.